

Preliminary

Harvatek Surface Mount CHIP LEDs Data Sheet B31B3BGR-10C-0005Q4



7				
Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
Specifications are subject	to changes for improvement without			
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DISCLAIMER	3
LIFE SUPPORT POLICY	3
PRODUCT SPECIFICATIONS	4
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION	4
LABEL SPECIFICATIONS	5
SPECIFICATIONS RANGE	6
PRODUCT FEATURES	7
ELECTRO-OPTICAL CHARACTERISTICS	
PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR RE	
SOLDERING	
CHARACTERISTICS OF B31B3BGR	
PRECAUTION FOR USE	10
PACKAGING	11
TAPE DIMENSION	11
REEL DIMENSION	12
Packing	12
DRY PACK	13
Baking	13
Precautions	13
REFLOW SOLDERING	14
Reworking	14
CLEANING	14
CAUTIONS OF PICK AND PLACE	15
Revise History	15

7						
	Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.	
	Tentative Product	******	******			
	Specifications are subject	to changes for improvement without				
advance notice. Proprietary data, drawings, company confidential		12/20/2018	Preliminary	Page 2/15		
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DISCLAIMER

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HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 3/15



Product Specifications

Item	Specification	Material	Quantity
Luminous	R: 45-360 mcd		
Intensity(Iv)	G: 71.5-450 mcd		
	B: 18-180 mcd		
	@10mA/ T _S = 25°C;Tolerance: <u>+</u> 10%		
Wavelength	R: 615.0-630.0 nm		
	G:515.0-530.0 nm		
	B: 460.0-472.0 nm		
	@10mA/ T _S = 25°C; Tolerance: <u>+</u> 0.5nm		
Vf	R: 1.6-2.4 V		
	G: 2.6-3.4 V		
	B: 2.6-3.4 V		
	@10mA/ T_S = 25°C ;Tolerance: \pm 0.05V		
Ir	< 1 μA @ V _R = 5V		
Resin	Clear	Ероху	
Carrier tape	EIA 481-1A specs	Conductive black tape	4000ea/reel
Reel	EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified
	•	•	•

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note: This is shipped test conditions

*Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

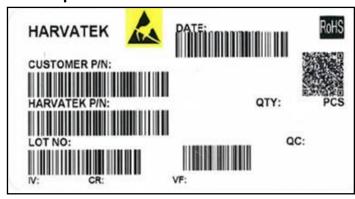
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

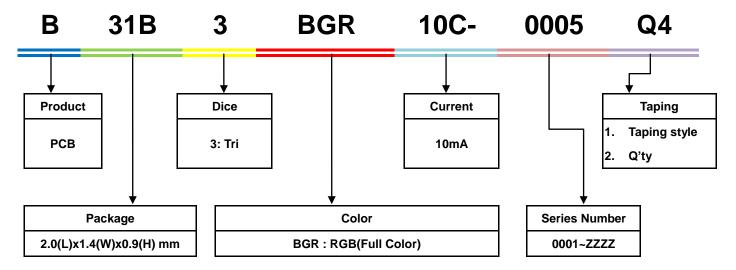
Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.	Data Sheet No.	
Tentative Product	******	******		
'	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 4/15



Label Specifications



Harvatek P/N:



Lot No.:

1 2	3	4	5	6	7	8	9	10
E 1	Α	1	Α	2	2	L	1	2
Code 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	1
Internal Tracing Code	2010-A 2011-B 2012-C 2013-D	1:Jan. 2:Feb. A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C 26:Z 27:7 28:8 29:9 30:3 31:4	01-	~ZZ		000~ZZZ	

Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.	Data Sheet No.	
Tentative Product	******	******		
1 '	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 5/15



Specifications Range

Luminous Intensity (Iv) Bin:

Luminous Intensity (Iv) Bin:R/G/B@20mA

	HT-B31B3BGR Series											
	IV											
	Red Green Blue											
Р	45	71.5	R	112.5	180	М	18	28.5				
Q	71.5	112.5	S	180	285	Ν	28.5	45				
R	112.5	180	Т	285	360	Р	45	71.5				
S	180	285	U	360	450	Q	71.5	112.5				
Т	285	360	V	450	560	R	112.5	180				

Note: It maintains a tolerance of ±10% on luminous intensity

Dominant Wavelength (λD) Bin:

	3 ()											
	HT-B31B3 BGR Series											
	WD											
Red Green						Blue						
Α	615	620	Α	515	520	Α	460	464				
В	620	625	В	B 520 525		В	464	468				
С	625	630	С	525	530	С	468	472				

Note: It maintains a tolerance of + 0.5nm on color

Forward Voltage (Vf) Bin:

	HT-B31B3BGR Series								
	VF								
Red Green						Blue			
E18 1.6 2.4 G38 2.6 3.4				G38	2.6	3.4			

Note: It maintains a tolerance of ±0.05V on forward voltage measurements

Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
· ·	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 6/15



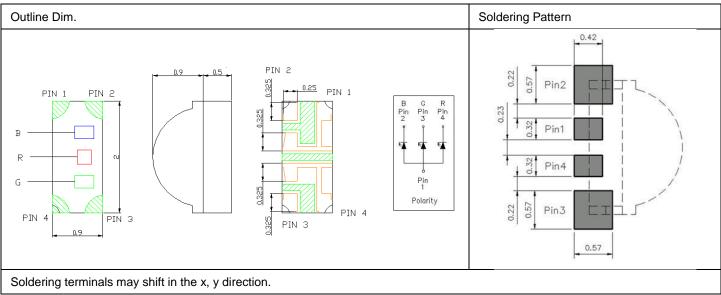
Product Features

Electro-Optical Characteristics

	1							(18	soldering, 25 °C)
Series Er	Emitting Color	Matarial	V _F	(V)	Wa	ivelength λ	(nm)	I _∨ (mcd)	Viewing
	Emilling Color	Material	typ	max	λ_{D}	λ_{P}	Δλ	Typical	Angle $2\theta \frac{1}{2}$
	Red	Red AllnGaP	2.0	2.4	620	627	16	115	X=120
			2.0	2.4	620				Y=104
DOADODOD	Green InGa		0.0	2.9 3.4	523	3 516	35	290	X=109
B31B3BGR		ingan	2.9						Y=111
	Dive	In CaN		3.4	467	404	461 22	55	X=113
	Blue	llue InGaN 2.	2.9			467 461			Y=113

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

(Unit:mm Tolerance: +/-0.1)



7				
Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
	Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential		Preliminary	Page 7/15



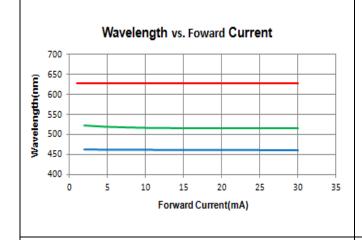
(T_{Soldering} 25°C)

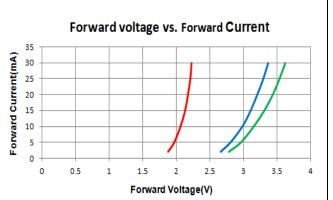
Absolute Maximum Ratings

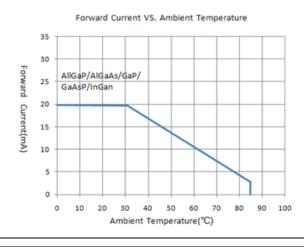
Series	P _D (mW)	V _R (V)	I _F (mA)	I _{FP} (mA)*	Top(°C)
Color	Power Dissipation	Reverse Reverse		Pulse Forward	Operating
Coloi	Fower Dissipation	Voltage	Forward Current	Current	Temperature
Red	30	5	10	≦20	
Green	40	5	10	≦20	-40~85
Blue	40	5	10	≦20	

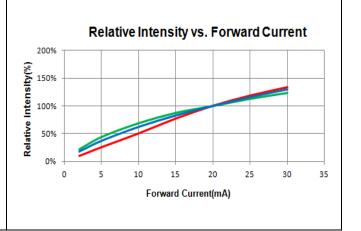
^{*}Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

Characteristics of B31B3BGR





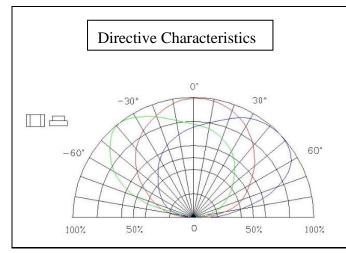


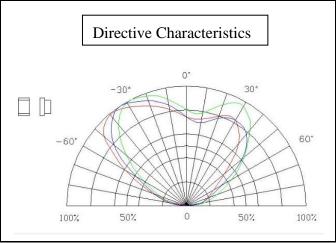


Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
, ,	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 8/15

^{*}Remarks:This product should be operated in forward bias.If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.







Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	*******		
'	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 9/15



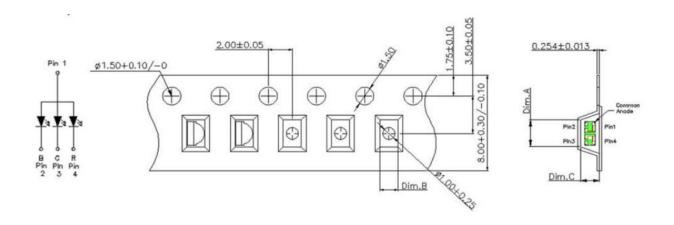
Precaution for Use

- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 4 weeks after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs.If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs.Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

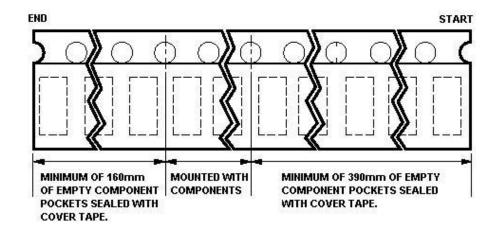
Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
'	to changes for improvement without data, drawings, company confidential	12/20/2018	Preliminary	Page 10/15



Packaging Tape Dimension



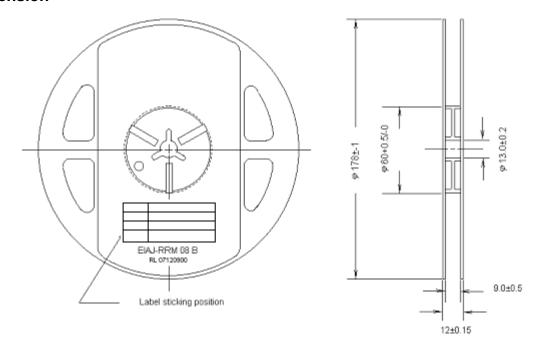
Dim. A	Dim. B	Dim. C	Q'ty/Reel
2.25±0.1	1.5±0.1	1.15±0.1	4K



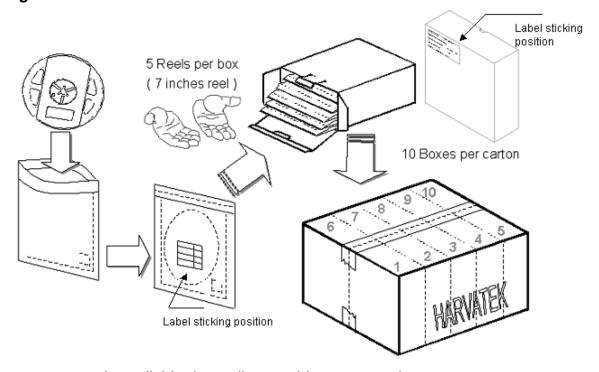
Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
'	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 11/15



Reel Dimension



Packing



5 boxes per carton is available depending on shipment quantity.

Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
'	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 12/15

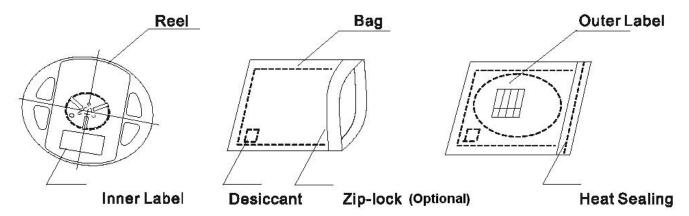


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Baking

Baking before soldering is recommended when the package has been unsealed for 4 weeks. The conditions are as followings:

- 1. $60\pm3^{\circ}$ C ×(12~24hrs)and<5%RH, taped reel type.
- 2. $100\pm3^{\circ}$ × (45min~1hr), bulk type.
- 3. $130\pm3^{\circ}$ C×(15min~30min), bulk type.

Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
'	to changes for improvement without a data, drawings, company confidential	12/20/2018	Preliminary	Page 13/15

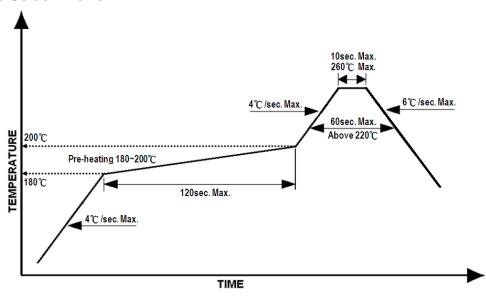


Reflow Soldering

Recommend soldering paste specifications:

- 1. Operating temp.: Above 220°C ,60 sec.
- 2. Peak temp.:260 °C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

7				
Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.
Tentative Product	******	******		
Specifications are subject to changes for improvement without				
advance notice. Proprietary data, drawings, company confidential		12/20/2018	Preliminary	Page 14/15
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Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revise History

Rev.	Descriptions	Date	Page
1.0	-	12/20/2018	-

7	7					
	Official Product	HT Part No. B31B3BGR-20C-0005Q4	Customer Part No.		Data Sheet No.	
	Tentative Product	******	*******			
	Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		12/20/2018	Preliminary	Page 15/15	
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